DECEMBER 1983 - REVISED MARCH 1988

- Package Options Include Plastic "Small Outline" Packages, Flat Packages, and Plastic and Ceramic DIPs
- Dependable Texas Instruments Quality and Reliability

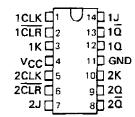
description

The '73, and 'H73, contain two independent J-K flip-flops with individual J-K, clock, and direct clear inputs. The '73, and 'H73, are positive pulse-triggered flip-flops. J-K input is loaded into the master while the clock is high and transferred to the slave on the high-to-low transition. For these devices the J and K inputs must be stable while the clock is high.

The 'LS73A contains two independent negative-edge-triggered flip-flops. The J and K inputs must be stable one setup time prior to the high-to-low clock transition for predictable operation. When the clear is low, it overrides the clock and data inputs forcing the Ω output low and the $\overline{\Omega}$ output high.

The SN5473, SN54H73, and the SN54LS73A are characterized for operation over the full military temperature range of $\sim 55\,^{\circ}\text{C}$ to $125\,^{\circ}\text{C}$. The SN7473, and the SN74LS73A are characterized for operation from $0\,^{\circ}\text{C}$ to $70\,^{\circ}\text{C}$.

SN5473, SN54LS73A . . . J OR W PACKAGE SN7473 . . . N PACKAGE SN74LS73A . . . D OR N PACKAGE (TOP VIEW)



73
FUNCTION TABLE

	INPUT	S		OUTPUTS		
CLR	CLK	Q	ā			
L	Х	Х	X	L	Н	
Н	JL.	L	L	00	$\overline{\mathbf{Q}}_{\mathbf{O}}$	
jн	J	Н	L	н	Ļ	
н	工	L	Н	L	н	
н	л	н	Н	TOG	GLE	

'LS73A FUNCTION TABLE

į	INPUT	rs		OUTF	UTS
CLR	CLK	J	К	a	
L	×	X	X	L	H
Н	1	L	L	00	\overline{a}_0
н	Į.	Н	L	Н	L
H	1	L	н	<u> </u> L	н
н	1	Н	Н	TOG	GLE.
Н	Н	х	×	αo	\bar{a}_0

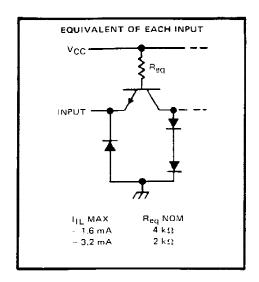
FOR CHIP CARRIER INFORMATION, CONTACT THE FACTORY

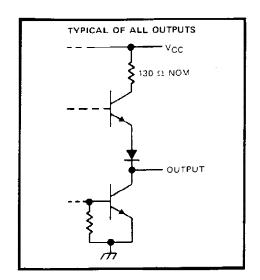
logic symbols† 'LS73A 73 1J <u>(14)</u> 1J <u>(14)</u> (12) 10 (12) 1J 1J ICLK (1) 1CLK (1) 1K (3) C1 > C1 1K (3) (<u>13)</u> 1<u>0</u> 1K 1K (13) 10 (2) 1CLR (2) P R 1CLR 2J (7) (7) (9) (9) 2J 2CLK (5) 20 20 (5) 2CLK (10) (10) 2K (8) 2К 2CLR (6) r 2CLR (6) 20 20

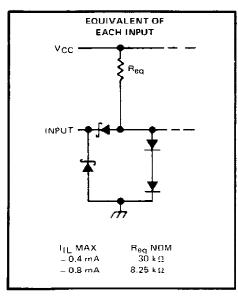
73

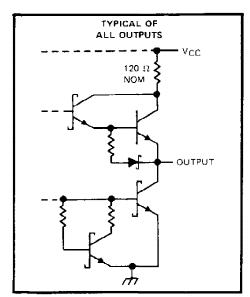
'LS73

schematics of inputs and outputs



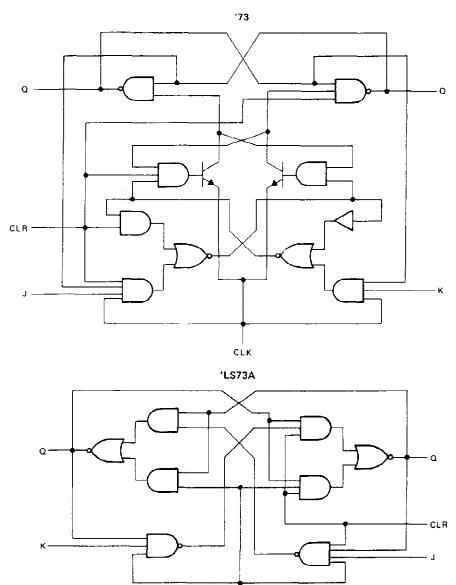






[†]These symbols are in accordance with ANSI/IEEE Std. 91-1984 and IEC Publication 617-12.

logic diagrams (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, VCC (See Note 1).			 	7 V
Input voltage: '73	. <i></i>	. <i></i>	 	5.5 V
LS73A				
Operating free-air temperature range	: SN54' .		 	-55°C to 125°C
· · ·	SN74'.		 	0° C to 70°C
Storage temperature range			 	-65°C to 150°C

CLK

NOTE 1: Voltage values are with respect to network ground terminal.



recommended operating conditions

				SN547	3		SN747	3	UNIT
			MIN	MOM	MAX	MIN	NOM	MAX	UNIT
Vcc	Supply voltage		4.5	5	6.5	4.75	5	5.25	٧
VIH	High-level input voltage		2			2			٧
VIL	Low-level input voltage				8.0			0.8	V
ЮН	High-level output current				- 0.4			- 0.4	mA
TOL	Low-level output current				16			16	mA
		CLK high	20			20			
tw	Pulse duration	CLK low	47			47			ns
		CLR low	25			25			
tsu	Input setup time before CLK f		0			0			ns
th	Input hold time data after CLK I		0			0			ns
TΑ	Operating free-air temperature		- 55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER			EST CONDITION	et		SN5473			SN7473		
PA	HAMEIEK	1.1	EST CONDITION	19,	MIN	TYP‡	MAX	MIN	TYP‡	MAX UNI - 1.5 V 0.4 V 1 mA 40 μA - 1.6 - 3.2 mA	UNIT
VIK	-	V _{CC} = MIN,	I _I = - 12 mA				- 1.5			- 1.5	V
Voн		V _{CC} = MIN, I _{OH} = - 0.4 mA	V _{IH} = 2 V,	V _{IL} = 0.8 V,	2.4	3.4		2.4	3.4		٧
VOL		V _{CC} = MIN, I _{OL} = 16 mA	V _{IH} = 2 V,	V _{IL} = 0.8 V,		0.2	0.4		0.2	0.4	٧
l _l		V _{CC} = MAX,	V _I = 5.5 V				1			1	mA
ΊΗ	Jor K CLR or CLK	V _{CC} = MAX,	V ₁ = 2.4 V	•			40 80				μА
	J or K	•		•			- 1.6			- 1.6	
I _{IL}	CLR	V _{CC} = MAX,	V; = 0.4 V				- 3.2			- 3.2	mA.
-	CLK						- 3.2			- 3.2	
108§		V _{CC} = MAX			- 20		- 57	- 18		- 57	MΑ
lcc*		V _{CC} = MAX,	See Note 2			10	20		10	20	mA

For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

NOTE 2: With all outputs open, ICC is measured with the Q and Q outputs high in turn. At the time of measurement, the clock input is grounded.

switching characteristics, $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$ (see note 3)

PARAMETER#	FROM (INPUT)	TO (TU9TUO)	TEST CONDITIONS	MIN	TYP	MAX	UNIT								
f _{max}				15	20		MHz								
tPLH	<u> </u>	CLB	CLB	CIB	CLB	CIB	I	I	CLR	<u> </u>			16	25	ns
tPHL .	CER	α	$R_{\perp} = 400 \Omega$, $C_{\perp} = 15 pF$		25	40	ns								
^t PLH	CLK	CLK Q or Q			16	25	пѕ								
^t PHL	CER	2014			25	40	ns								

[#]fmax = maximum clock frequency: tpLH = propagation delay time, low-to-high-level output; tpHL = propagation delay time, high-to-low-level output.

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.



 $^{^\}ddagger$ All typical values are at V_{CC} = 5 V, T_A = 25 °C.

[§] Not more than one output should be shorted at a time.

Average per flip-flop.

recommended operating conditions

			SN54LS73A			SI	174LS7	3A	
		<u> </u>	MIN	МОМ	MAX	MIN	NOM	MAX	UNIT
Vcc	Supply voltage		4.5	5	5.5	4.75	5	5.25	V
VIH	High-level input voltage	-	2			2			V
VIL	Low-level input voltage				0.7			0.8	V
Гон	High-level output current				- 0.4			- 0.4	mΑ
loL	Low-level output current				4			8	mΑ
fclock	Clock frequency		0		30	0		30	MHz
	Pulse duration	CLK high	20			20			
tw	Pulse duration	CLR low	25			20			ns
	Control of the CLK	data high or low	20			20			-
t _{su}	Set up time-before CLK I	CLR inactive	20	٠		20			пs
τh	Hold time-data after CLK↓		0			0			ns
TA	Operating free-sir temperature		- 55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		-	EST CONDITION	et .	SI	N54LS7:	3A	SN74LS73A]	
		TEST CONDITIONS [†]		MIN	TYP\$	MAX	MIN	TYP‡	MAX	UNIT		
V _{IK}		V _{CC} = MIN,	I₁ = - 18 mA				- 1.5			— 1.5	V	
۷он		V _{CC} = MIN, 1 _{OH} = - 0.4 mA	V _{IH} = 2 V,	VIL = MAX,	2.5	3.4		2.7	3.4		٧	
		V _{CC} = MIN, V _{IL} = MAX, V _{IH} = 2 V, 0.25 0.4			0.25	0.4	V					
VOL		V _{CC} = MIN,	VIL = MAX,	V _{1H} = 2 V,					0.35	0.5]	
	J or K						0.1			0.1		
Ц	CLA	V _{CC} = MAX,	$C = MAX$, $V_{\parallel} = 7 V$				0.3			0.3	mA	
	CLK	1					0.4			0.4	<u> </u>	
	J or K		V ₁ = 2.7 V				20			20		
Ιн	CLR	V _{CC} = MAX,					60			60_	μΑ	
	CLK						80			80	1	
	J or K						- 0.4			- 0 <u>.4</u>		
11L	CLR or CLK	V _{CC} = MAX,	v j = u.4 V			·	- 0.8			- 0.8	mA	
los§		V _{CC} = MAX,	See Note 4		_ 20		_ 100	- 20		100	mA	
ICC (T	otal)	VCC = MAX,	See Note 2	•	1	4	6		4	6	mA	

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

switching characteristics, $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$ (see note 3)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	MIN	TYP	MAX	UNIT
f _{max}				30	45		MHz
^t PLH	CLR or CLK	Q or Q	$R_{\perp} = 2 k\Omega$, $C_{\perp} = 15 pF$		15	20	п\$
tpH1	CEITOICER	2012			15	20	nş

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.



[‡] All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$.

[§] Not more than one output should be shorted at a time, and the duration of the short circuit should not exceed one second.

NOTE 2: With all outputs open, I_{CC} is measured with the Q and Q outputs high in turn. At the time of measurement, the clock input is grounded.

NOTE 4: For certain devices where state commutation can be caused by shorting an output to ground, an equivalent test may be performed with $V_{\rm C}$ = 2.25 V and 2.125 V for the 54 family and the 74 family, respectively, with the minimum and maximum limits reduced to one half of their stated values.

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